L	Hits	Search Text	DB	Time stamp
Number				
1	539	356/237.2.ccls.	USPAT;	2003/07/15
			US-PGPUB;	14:29
			EPO; JPO;	
			DERWENT	
2	1986	356/237.1.ccls.	USPAT;	2003/07/15
			US-PGPUB;	14:30
•			EPO; JPO;	
			DERWENT	
4	3	356/237.1.ccls. and ((micro near defects)	USPAT;	2003/07/15
		and (macro near defects))	US-PGPUB;	14:31
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
	,		DERWENT	
з .	38	(micro near defects) and (macro near	USPAT;	2003/07/15
		defects)	US-PGPUB;	14:54
		402000)	EPO; JPO;	1
			DERWENT	
5	65	4618938.URPN.	USPAT	2003/07/15
. `	05	4010930.0KFN.	OSFAI	14:37
6	12	("4185298" "4218142" "4295198"	USPAT	2003/07/15
0	12	"4325077" "4334241" "4389669"	USPAI	14:37
		"4475122" "4481664" "4486776"		14:37
7	604	"4508453" "4532650" "4556317").PN. both near4 sides near4 inspect\$4	HCDAM.	2002/07/15
′	604	both hear4 sides hear4 inspects4	USPAT;	2003/07/15
			US-PGPUB;	14:54
			EPO; JPO;	
		1-6	DERWENT	2002/07/15
8	37		USPAT;	2003/07/15
		inspect\$4)	US-PGPUB;	15:46
			EPO; JPO;	
_			DERWENT	
9	2	6031615.pn.	USPAT;	2003/07/15
			US-PGPUB;	15:03
			EPO; JPO;	
	_	5006761	DERWENT	
10	1	5986761.URPN.	USPAT	2003/07/15
				15:03
11	5		USPAT	2003/07/15
		"4427295" "5581353").PN.		15:22
12	2	5872632.pn.	USPAT;	2003/07/15
			US-PGPUB;	15:47
			EPO; JPO;	
			DERWENT	
13	6	5872632.URPN.	USPAT	2003/07/15
				15:48
14	4		USPAT	2003/07/15
		"5410162").PN.		15:48

L Number	Hits	Search Text	DB	Time stamp
1	2927	<pre>critical near3 dimension\$ same (measur\$4 or detect\$4 or determin\$4)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 09:45
2	75114	356/\$.ccls.	USPAT; US-PGPUB; EPO; JPO;	2003/07/15 09:51
3	221	(critical near3 dimension\$ same (measur\$4 or detect\$4 or determin\$4)) and 356/\$.ccls.	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/07/15 09:39
4	286443	wafer	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 09:40
5	147	((critical near3 dimension\$ same (measur\$4 or detect\$4 or determin\$4)) and 356/\$.ccls.) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 09:42
6	4184	pump near4 beam	USPAT; US-PGPUB; EPO; JPO;	2003/07/15
7	6345	probe near4 beam	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/07/15 09:43
8	409	(pump near4 beam) and (probe near4 beam)	DERWENT USPAT; US-PGPUB; EPO; JPO;	2003/07/15 09:43
9	. 2	(critical near3 dimension\$ same (measur\$4 or detect\$4 or determin\$4)) and ((pump near4 beam))	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15
10	1172	critical near3 dimension\$ near4(measur\$4 or detect\$4 or determin\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 09:45
11	1	((pump near4 beam) and (probe near4 beam)) and (critical near3 dimension\$ near4 (measur\$4 or detect\$4 or determin\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 10:23
12	24541	1 1 1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15
13	23	(critical near3 dimension\$ near4(measur\$4 or detect\$4 or determin\$4)) and (pump and probe)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15
14	106	356/\$.ccls. and (critical near3 dimension\$ near4(measur\$4 or detect\$4 or determin\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15
15	16	5757507.URPN.	USPAT	2003/07/15
16	6	("4529314" "4568189" "4820055" "5216257" "5262258" "5402224").PN.	USPAT	2003/07/15
17	9	4863548.URPN.	USPAT	2003/07/15
18	2	("4141780" "4650744").PN.	USPAT	2003/07/15
19	2	6054868.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15

DOCUMENT-IDENTIFIER: US 20030025905 A1

TITLE: Method of detecting and

classifying scratches,

particles and pits on thin

film disks or wafers

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Detail Description Paragraph - DETX (21): [0073] A problem in the magnetic recording industry is to inspect thin film disks for defects at the final test step of the manufacturer of disks. The manufacturers of thin film disks require that both sides of the thin film disk be inspected simultaneously. The problem is that the clearance between the disk and the chuck (which holds the disk) is only 1" or less (see FIG. 13, 1304). This requires that the optics be miniaturized in order to fit in the small space between the disk and the chuck (see FIG. 13). A solution to this problem can be obtained by using the optical designs in FIG. 8, 9, 10, and 11. These designs have several key improvements, which allow the design to be miniaturized without compromising the performance of the device. First of all the design uses the internal feedback photodiode, which is included within the laser diode 801, to achieve stabilization of the DC level of the optical signal. Secondly, the angle of incidence, .theta., is adjusted to reduce the height of the instrument so that it will fit within

the 1" space requirement. Thirdly, the surface topography measurement capability feature of the instrument is incorporated within the phase/specular detectors 808 and 809 shown in FIGS. 8 and 9. The position sensitive detectors 808 and 809 (quadrant detectors) serve as both phase detectors, specular detectors, and topography measurement detectors. Fourthly, the size may be decreased by using a polarizing beam splitter 901 as shown in FIG. 9 instead of a Wollaston prism 807 as shown in FIG. 8. The polarizing beam splitter 807 or Wollaston prism 901 is rotated at 45.degree. with respect to the plane of incidence.

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